(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
16 May 2013 (16.05.2013)

WIPO | PCT

(10) International Publication Number
WO 2013/070978 A4

(51) International Patent Classification:
H01L 21/677 (2006.01) *H01L 21/687* (2006.01)

(21) International Application Number:
PCT/US2012/064241

(22) International Filing Date:
8 November 2012 (08.11.2012)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
61/557,363 8 November 2011 (08.11.2011) US

(71) Applicant: **INTEVAC, INC.** [US/US]; 3560 Bassett Street, Santa Clara, CA 95054 (US).

(72) Inventors; and
(71) Applicants : **PEDERSON, Terry** [US/US]; 1547 Nuthatch Lane, Sunnyvale, CA 94087 (US). **HIESLMAIR, Henry** [US/US]; 545 Dawn Drive, Sunnyvale, CA 94087 (US). **CHUN, Moon** [US/US]; 852 Foxworthy Avenue, San Jose, CA 95125 (US). **PRABHAKAR, Vinay** [IN/US]; 175 Calvert Drive, Apt # N202, Cupertino, CA 95014 (US). **ADIBI, Babak** [US/US]; 439 Knoll Drive, Los Altos, CA 94024 (US). **BLUCK, Terry** [US/US]; 3128 Butte Street, Santa Clara, CA 95051 (US).

(74) Agent: **BACH, Joseph**; Nixon Peabody LLP, 401 9th Street, N.W. Suite 900, Washington, DC 20004 (US).

(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report (Art. 21(3))*

— *with amended claims and statement (Art. 19(1))*

[Continued on next page]

(54) **Title**: SUBSTRATE PROCESSING SYSTEM AND METHOD

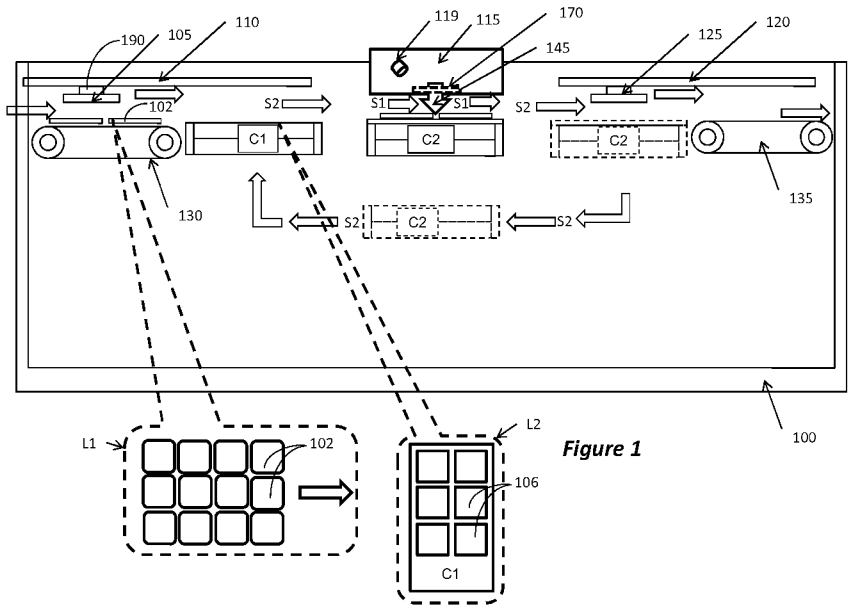


Figure 1

(57) **Abstract**: A system for processing substrates has a vacuum enclosure and a processing chamber situated to process wafers in a processing zone inside the vacuum enclosure. Two rail assemblies are provided, one on each side of the processing zone. Two chuck arrays ride, each on one of the rail assemblies, such that each is cantilevered on one rail assemblies and support a plurality of chucks. The rail assemblies are coupled to an elevation mechanism that places the rails in upper position for processing and at lower position for returning the chuck assemblies for loading new wafers. A pickup head assembly loads wafers from a conveyor onto the chuck assemblies. The pickup head has plurality of electrostatic chucks that pick up the wafers from the front side of the wafers.

WO 2013/070978 A4

WO 2013/070978 A4

(88) **Date of publication of the international search report**: 8 August 2013

Date of publication of the amended claims and statement: 26 September 2013